

## Features

- Advanced Trench MOS Technology
- Low Gate Charge
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available

## Product Summary

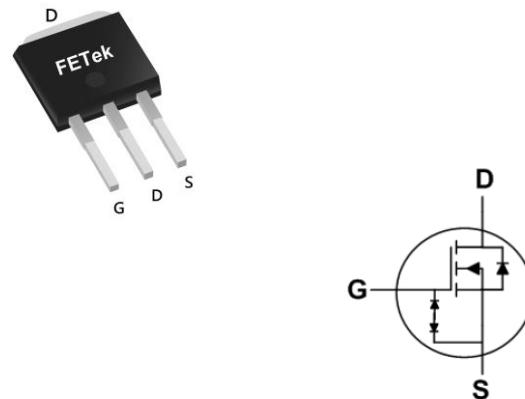


BVDSS	RDS(on)	ID
60V	8.5mΩ	60A

## Applications

- Motor Control.
- DC/DC Converter.
- Synchronous rectifier applications.

## TO251 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current <sup>1,6</sup>	60	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current <sup>1,6</sup>	38	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	120	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	64.8	mJ
$I_{AS}$	Avalanche Current	36	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	52	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	60	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.4	°C/W

Electrical Characteristics ( $T_J=25^\circ C$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=20A$	---	6.3	8.5	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$	---	10.8	12.5	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	2.0	2.3	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 10$	$\mu A$
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	3	---	$\Omega$
$Q_g$	Total Gate Charge( $V_{GS}=4.5V$ )	$V_{DS}=30V, V_{GS}=4.5V, I_D=20A$	---	11.9	---	$nC$
$Q_{gs}$	Gate-Source Charge		---	3.7	---	
$Q_{gd}$	Gate-Drain Charge		---	6.0	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=2.2\Omega,$ $I_D=20A$	---	7	---	$ns$
$T_r$	Rise Time		---	4.5	---	
$T_{d(off)}$	Turn-Off Delay Time		---	28	---	
$T_f$	Fall Time		---	3.5	---	
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, f=1MHz$	---	1010	---	$pF$
$C_{oss}$	Output Capacitance		---	348	---	
$C_{rss}$	Reverse Transfer Capacitance		---	25	---	

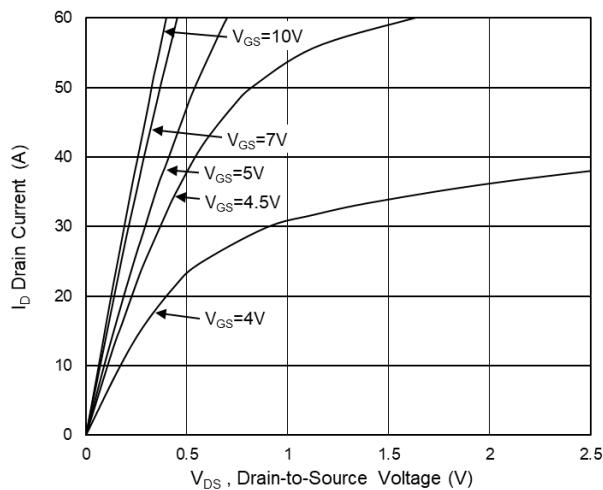
## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5,6</sup>	$V_G=V_D=0V$ , Force Current	---	---	60	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_s=1A, T_J=25^\circ C$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, dI/dt=100A/\mu s$ ,	---	21	---	$nS$
		$T_J=25^\circ C$	---	70	---	$nC$

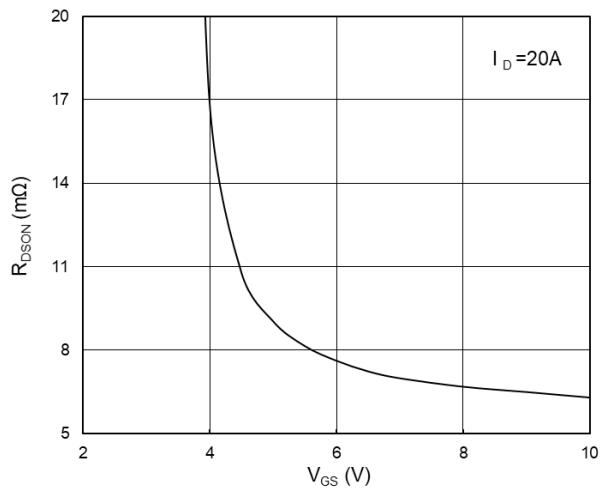
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=36A$
- 4.The power dissipation is limited by  $150^\circ C$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.
- 6.The maximum current rating is package limited.

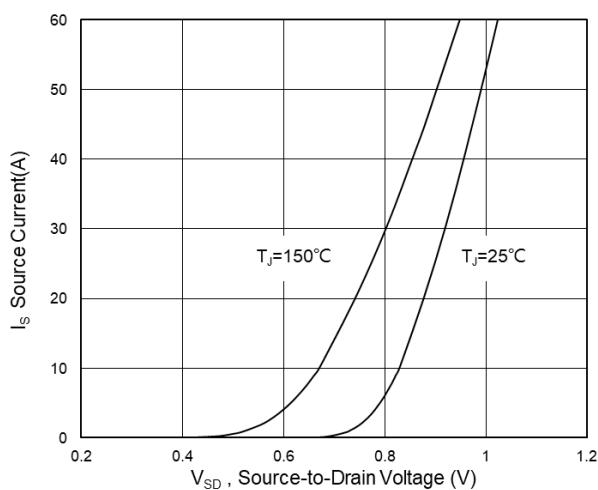
### Typical Characteristics



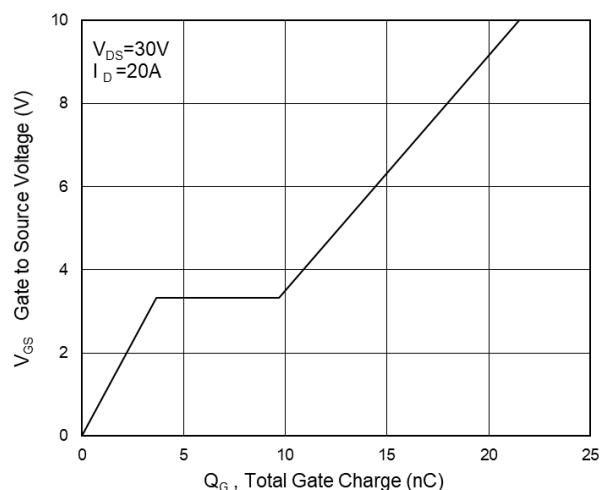
**Fig.1 Typical Output Characteristics**



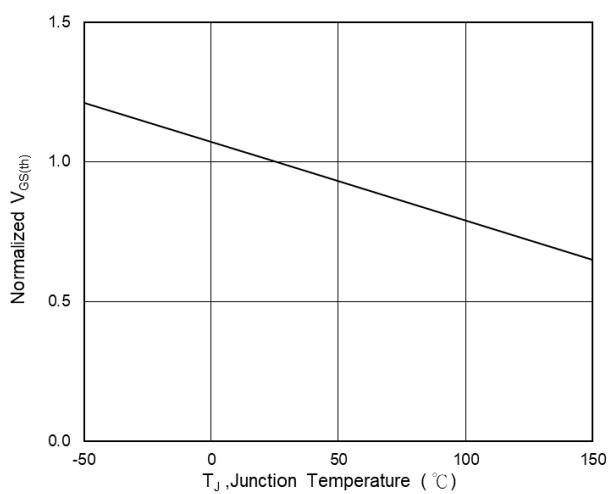
**Fig.2 On-Resistance vs G-S Voltage**



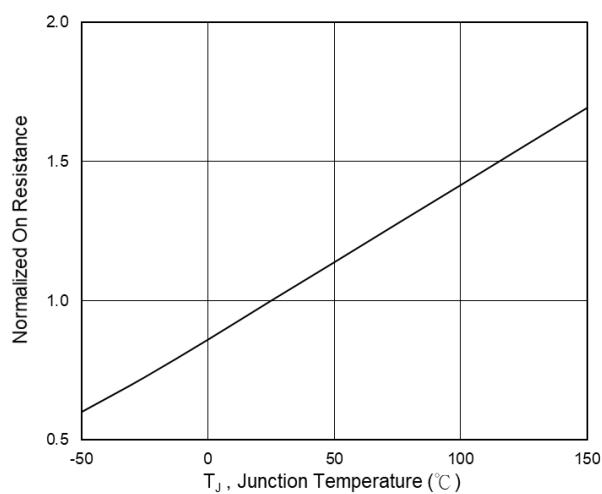
**Fig.3 Source Drain Forward Characteristics**



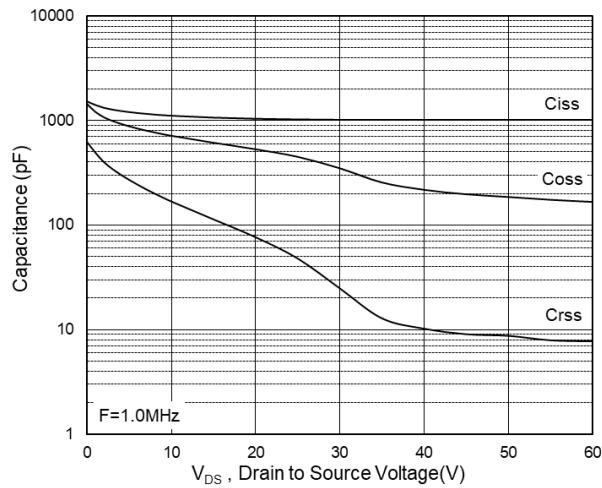
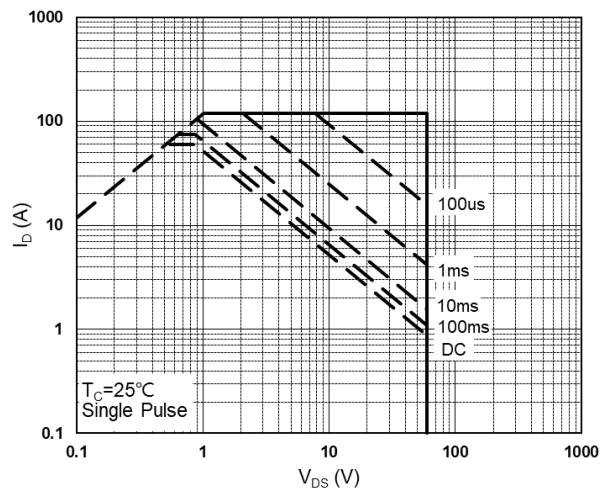
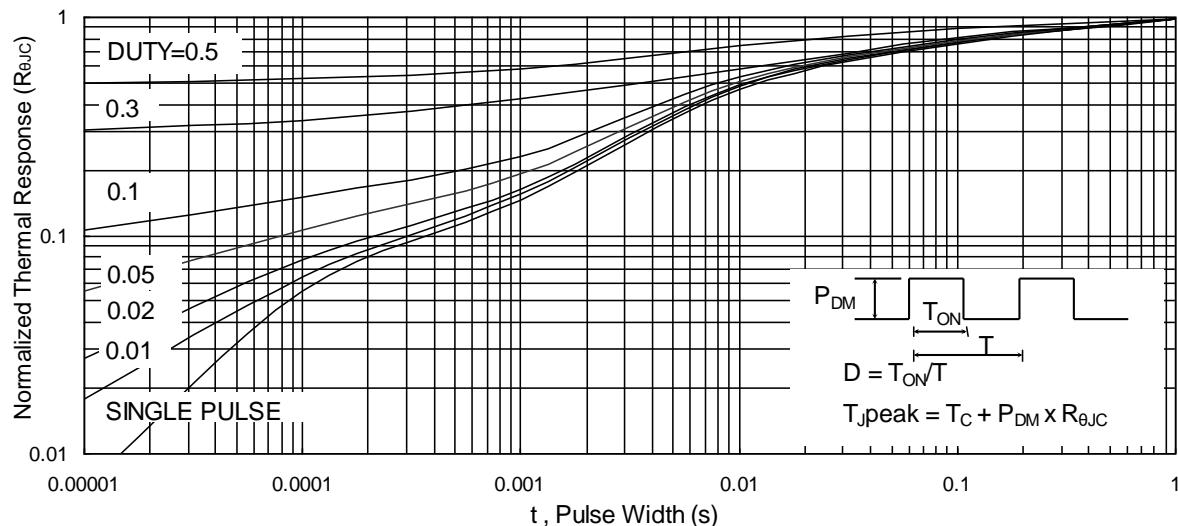
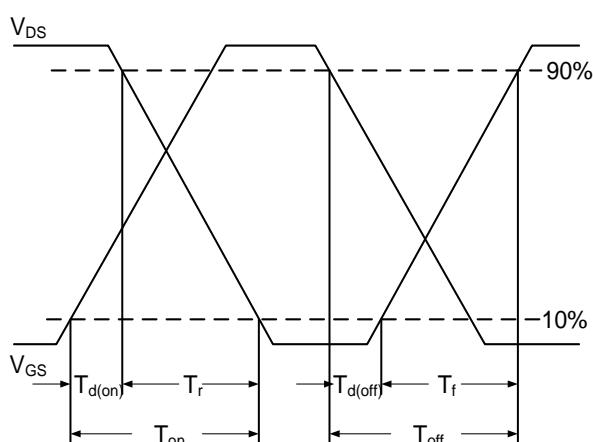
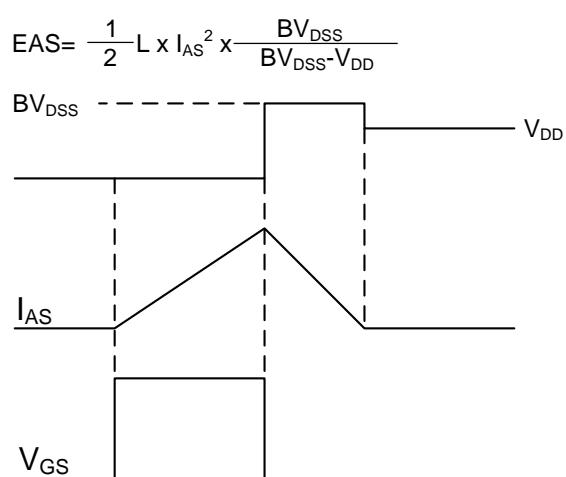
**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**